

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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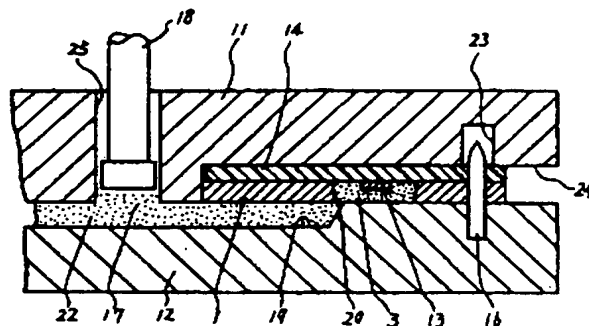
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INVENTOR : SATO TADAAKI;

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TITLE : RESIN SEALING



ABSTRACT : PURPOSE: To seal by resin without making the sealing resin contact with the substrate other than the specified sealed region by a method wherein the transfer molding is performed using a cavity made by trimming a plate material separate from the sealing die.

CONSTITUTION: A concave 24 in which a printed circuit board 14 or a lead frame on which an electronic component 13 is mounted, a piercing hole 25 into which a plunger head 18 is inserted and a pilot hole 23 for positioning are provided to the upper die 11. A runner 19 through which sealing resin 22 is introduced and a gauge pin 16 are provided to the lower die 12. The positioning of the printed circuit board 14 and the upper die 11 is made by inserting the gauge pin 16 of the lower die 12 into the pilot hole. The dice are clamped by a molding press and the sealing resin 22 put into a pot 17 is heated and melted and lead into a cavity 3 so as to fill it. The sealing resin in the runner 19 does not touch the board 14, so that the damage of the board 14 is avoided.

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